

MIC4467/4468/4469

Quad 1.2A-Peak Low-Side MOSFET Driver

Bipolar/CMOS/DMOS

General Description

The MIC4467/8/9 family of 4-output CMOS buffer/drivers is an expansion from the earlier single- and dual-output drivers, to which they are functionally closely related. Because package pin count permitted it, each driver has been equipped with a 2-input logic gate for added flexibility. Placing four high-power drivers in a single package also improves system reliability and reduces total system cost. In some applications, one of these drivers can replace not only two packages of singleinput drivers, but some of the associated logic as well.

Although primarily intended for driving power MOSFETs, and similar highly capacitive loads, these drivers are equally well suited to driving any other load (capacitive, resistive, or inductive), which requires a high-efficiency, low-impedance driver capable of high peak currents, rail-to-rail voltage swings, and fast switching times. For example, heavily loaded clock lines, coaxial cables, and piezoelectric transducers can all be driven easily with MIC446X series drivers. The only limitation

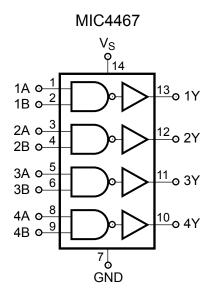
Features

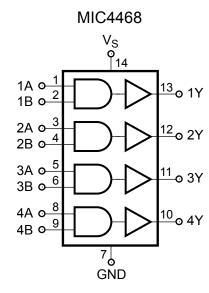
- Built using reliable, low power CMOS processes
- Latchproof. Withstands 500mA Inductive Kickback
- 3 Input Logic Choices
- Symmetrical Rise and Fall Times......25ns Short, Equal Delay Times75ns
- High Peak Output Current...... 1.2A Wide Operating Range4.5 to 18V
- Low Equivalent Input Capacitance (typ) 6pF
- Inputs = Logic 1 for Any Input From 2.4V to V_c
- **ESD Protected**

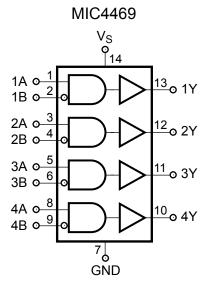
Applications

- General-Purpose CMOS Logic Buffer
- Driving All 4 MOSFETs in an H-Bridge
- Direct Small-Motor Driver
- Relay or Peripheral Drivers
- **Dual Differential Output Power Drivers**
- **CCD** Driver
- Pin-Switching Network Driver

Logic Diagrams







on loading is that total power dissipation in the IC must be kept within the power dissipation limits of the package.

The MIC446X series drivers are built using a BCD process. They will not latch under any conditions within their power and voltage ratings. They are not subject to damage when up

to 5V of noise spiking (either polarity) occurs on the ground line. They can accept up to half an amp of inductive kickback current (either polarity) into their outputs without damage or logic upset.

Ordering Information

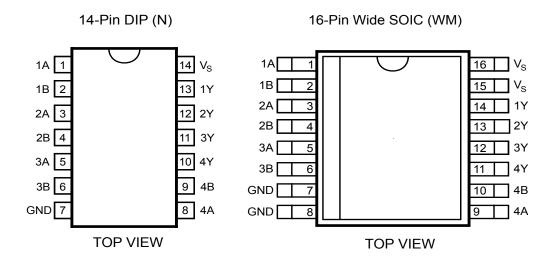
Part Number		Temperature		
Standard	Pb-Free	Range	Package	
MIC44xxCN*	MIC44xxZN*	0°C to +70°C	14-pin Plastic DIP	
MIC44xxCWM*	MIC44xxZWM*	0°C to +70°C	16-pin Wide SOIC	
MIC44xxBN*	MIC44xxYN*	–40°C to +85°C	14-pin Plastic DIP	
MIC44xxBWM*	MIC44xxYWM*	–40°C to +85°C	16-pin Wide SOIC	

^{*} xx identifies input logic:

Truth Table

	Inp	Output		
Part No.	Α	В	Υ	
MIC4467 (Each Driver)	L X H	ΧLΗ	H H L	
MIC4468 (Each Driver)	H L X	H X L	H L L	
MIC4469 (Each Driver)	L X H	X H L	L L H	

Pin Configurations

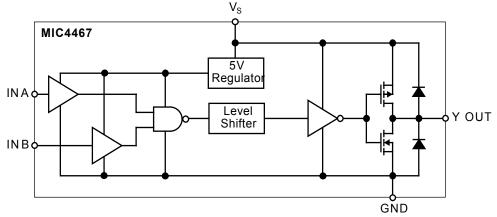


^{67 —} NAND 68 — AI

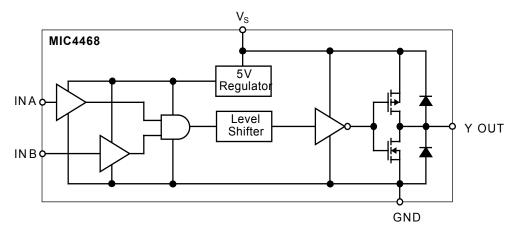
^{68 —} AND 69 — AND with 1 inverting input

^{**}Pb-Free industrial grade PDIP available in MIC4468 & MIC4469 only.

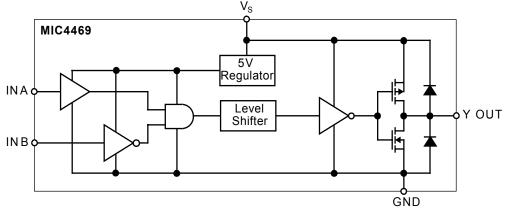
Block Diagrams



Functional Diagram for One Driver (Four Drivers per Package-Ground Unused Inputs)



Functional Diagram for One Driver (Four Drivers per Package-Ground Unused Inputs)



Functional Diagram for One Driver (Four Drivers per Package-Ground Unused Inputs)

Absolute Maximum Ratings (Notes 1 and 2)

Supply Voltage 22V **Power Dissipation**

Input Voltage (GND – 5V) to $(V_s + 0.3V)$ N Package (14-Pin Plastic DIP) 1.5W

Maximum Chip Temperature WM Package (16-Pin Wide SOIC)

1W Operating 150°C

Storage -65° to +150°C Package Thermal Resistance

N Package (14-Pin Plastic DIP) θ_{JA} WM Package (16-Pin Wide SOIC) θ_{JA} Maximum Load Temperature 80°C/W (10 sec, for soldering) 300°C 120°C/W

Operating Ambient Temperature

C Version 0° to +70°C **B** Version -40° to +85°C

Electrical Characteristics: Measured at $T_A = 25^{\circ}\text{C}$ with $4.5\text{V} \le \text{V}_S \le 18\text{V}$ unless otherwise specified. (**Note 3**)

Symbol	Parameter	Conditions	Min	Тур	Max	Units
INPUT			l			
V _{IH}	Logic 1 Input Voltage		2.4	1.3		V
V _{IL}	Logic 0 Input Voltage			1.2	0.8	V
I _{IN}	Input Current	$0 \le V_{IN} \le V_{S}$	-1		1	μA
OUTPUT					•	•
V _{OH}	High Output Voltage	I _{LOAD} = 10mA	V _s -0.15			V
V _{OL}	Low Output Voltage	I _{LOAD} = 10mA			0.15	V
R _o	Output Resistance	I _{OUT} = 10mA, V _S = 18V		5	15	Ω
I _{PK}	Peak Output Current			1.2		А
I	Latch-Up Protection Withstand Reverse Current		>500			mA
SWITCHIN	IG TIME				•	•
t _R	Rise Time	Test Figure 1		14	25	ns
t _F	Fall Time	Test Figure 1		13	25	ns
t _{D1}	Delay Time	Test Figure 1		30	75	ns
t _{D2}	Delay Time	Test Figure 1		45	75	ns
POWER S	UPPLY	·				
I _s	Power Supply Current Supply			0.2	4	mA

Note 3. Specification for packaged product only.

Electrical Characteristics:

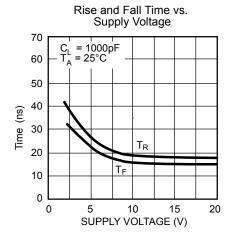
Measured over operating temperature range with 4.5V \leq V $_{\rm S}$ \leq 18V unless otherwise specified.

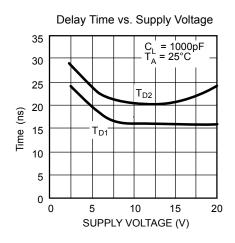
Symbol	Parameter	Conditions	Min	Тур	Max	Units
INPUT	<u>'</u>		l .			
V _{IH}	Logic 1 Input Voltage		2.4	1.4		V
V _{IL}	Logic 0 Input Voltage			1.0	0.8	V
I _{IN}	Input Current	$0 \le V_{IN} \le V_{S}$	-1		1	μΑ
OUTPUT						
V _{OH}	High Output Voltage	I _{LOAD} = 10 mA	V _s -0.3			V
V _{OL}	Low Output Voltage	I _{LOAD} = 10 mA			0.3	V
R _o	Output Resistance	I _{OUT} = 10 mA, V _S = 18V		7	30	Ω
I _{PK}	Peak Output Current			1.2		А
I	Latch-Up Protection Withstand Reverse Current		500			mA
SWITCHIN	NG TIME					•
t _R	Rise Time	Test Figure 1		17	50	ns
t _F	Fall Time	Test Figure 1		16	50	ns
t _{D1}	Delay Time	Test Figure 1		35	100	ns
t _{D2}	Delay Time	Test Figure 1		55	100	ns
POWER S	SUPPLY	ı	<u> </u>	ļ.	1	
Is	Power Supply Current Supply			0.4	8	mA

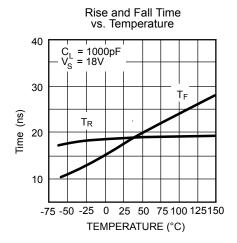
NOTE 1: Functional operation above the absolute maximum stress ratings is not implied.

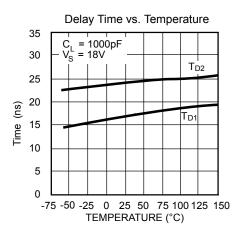
NOTE 2: Static sensitive device. Store only in conductive containers. Handling personnel and equipment should be grounded to prevent static damage.

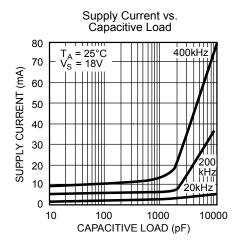
Typical Characteristics

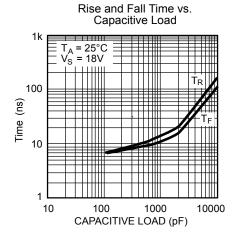


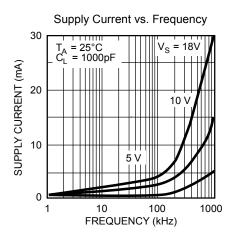


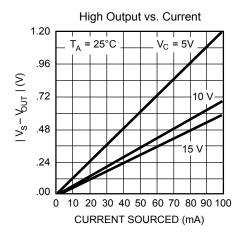


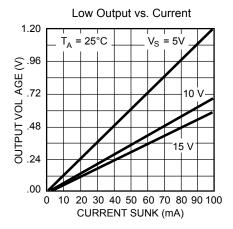


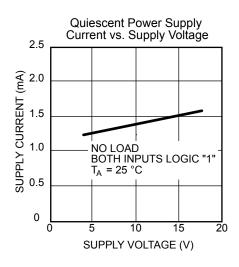


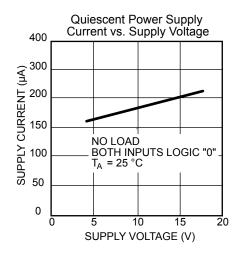




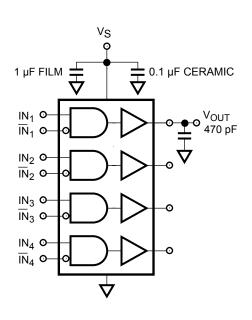


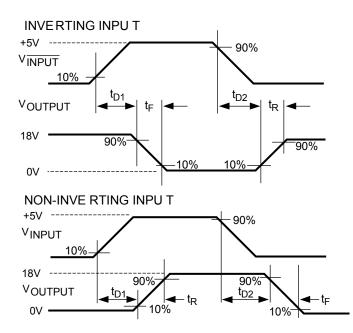




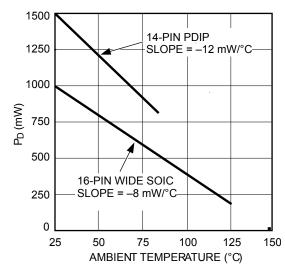


Test Figure 1

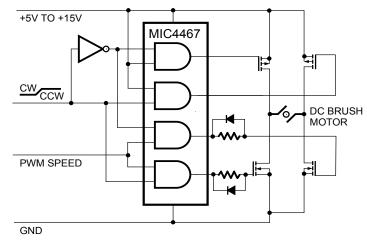




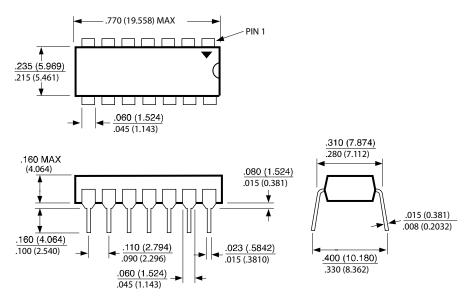
Package Power Dissipation



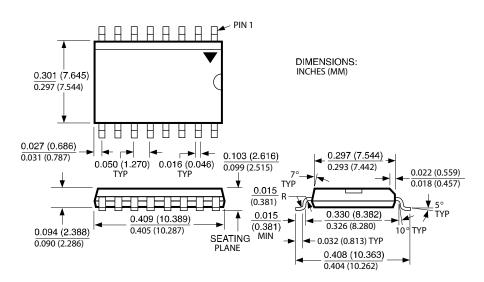
Quad Driver Drives H Bridge to Control Motor Speed and Direction



Package Information



14-Pin Plastic DIP (N)



16-Pin Wide SOP (WM)

MICREL INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB http://www.micrel.com

This information furnished by Micrel in this data sheet is believed to be accurate and reliable. However no responsibility is assumed by Micrel for its use.

Micrel reserves the right to change circuitry and specifications at any time without notification to the customer.

Micrel Products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is a Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 1998 Micrel, Inc